

PATENT ABSTRACTS OF JAPAN

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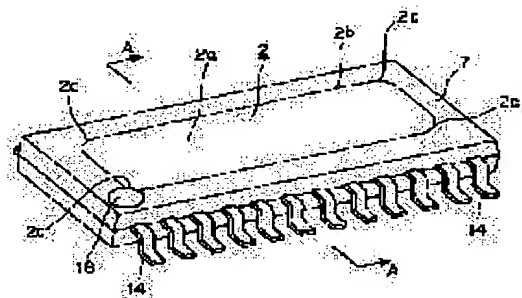
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(54) SEMICONDUCTOR PACKAGE INCORPORATING HEAD SPREADER

(57)Abstract:

PURPOSE: To protect the mold resin against crack in the vicinity of corner part on the peripheral face of a heat spreader.

CONSTITUTION: An IC chip is bonded to one side of a heat spreader 2 in a package and a lead frame 14 is also bonded while keeping insulation and then the IC chip is wire bonded to the lead frame 14. It is then subjected entirely to transfer molding of mold resin 7 while exposing the other surface 2a of the heat spreader 2. Each corner part of the peripheral surface 2a of the heat spreader 2 covered with the mold resin 7 is rounded. This structure restrains concentration of stress due to the difference of thermal expansion coefficient between the heat spreader 2 and the mold resin 7 in the vicinity of each corner part 2c when the temperature drops thus suppressing the occurrence of crack.



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